


MATERIAL DECLARATION SHEET



Material Number	CRT0402-AS Series			
Product Line	Thin Film Precision Chip Resistor			
Compliance Date	2015/09/17			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Substrate	Ceramics 708S	0.51395	Aluminum oxide	1344-28-1	96	89.948	93.696
				Silicon dioxide	14808-60-7	3	2.811	
				Magnesium oxide	1309-48-4	1	0.937	
2	Backside Electrode	SR4350	0.0062	Silver	7440-22-4	85	0.6248	1.136
				Copper oxide	1317-38-0	15	0.5112	
3	Primary Upside Electrode	SR4350	0.0062	Silver	7440-22-4	85	0.6248	1.136
				Copper oxide	1317-38-0	15	0.5112	
4	Secondary Upside Electrode	DS-7260THM(T)	0.0062	Silver	7440-22-4	84.1	0.955	1.136
				Nickel	7440-02-0	2.4	0.028	
				Phenoxy resin	25068-38-6	6.1	0.069	
				Epoxy resin	29690-82-2	3.7	0.042	
				Phenol resin	24979-74-6	3.7	0.042	
5	Overcoat	OHMCOAT 1055B	0.0050	Resins	Trade secret	39.8	0.360	0.906
				Carbon Black	1333-86-4	3.4	0.031	
				Silicon dioxide	60676-86-0	22.7	0.206	
				Talc	14807-96-6	11.4	0.103	
				Additives	Trade secret	22.7	0.206	
6	Nickel Plating	Electrolytic Nickel	0.0015	Nickel	7440-02-0	100	0.264	0.264
7	Tin Plating	Pure tin Solder	0.0034	Tin	7440-31-5	100	0.623	0.623
8	Edge Electrode	Conductor	0.00055	Nickel	7440-02-0	56	0.056	0.100
				Chromium	7440-47-3	44	0.044	

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9	Resistor Layer	Conductor	0.0055	Nickel	7440-02-0	56	0.562	1.003
				Chromium	7440-47-3	44	0.441	
		Total weight	0.5485					

This Document was updated on: 2015/09/17

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.